

Novel Inorganic Fillers for Next-generation Semiconductor Packaging

A global chemical and materials company is seeking **novel inorganic fillers for semiconductor packaging**. Traditionally, inorganic fillers are used with polymer binders such as epoxy resin for semiconductor packaging, however some new properties are required for the next generation. Our client is seeking **improved or novel inorganic fillers** for this purpose. Inorganic fillers developed for other applications (e.g. solar energy) that have suitable properties for use in semiconductor packaging are also of interest.



Approaches of Interest:

- Materials with a **low dielectric constant** and **low or negative coefficient of thermal expansion** are of highest interest. **High thermal conductivity** is also preferred
- The size of the filler should range from **tens of nanometers to tens of micrometers**
- Spherical, rod, plate, and needle shaped fillers are of interest. Preparation methods that allow for **control over the particle shape** are of highest interest
- **Ceramic-based materials** are of particular interest

Out of Scope:

- Conductive metals and carbon fillers are out of scope for this campaign

Developmental Stages of Interest:

Our client is interested in opportunities at all stages of development.






Submission Information

Submission of one page, 200-300 word briefs are encouraged, along with any optional supplementary information e.g. relevant publications. In submitting to this campaign, you confirm that your submission contains only non-confidential information.

Opportunity for Collaboration

Our client is open to a range of collaboration opportunities, with the most appropriate outcome being decided on a case-by-case basis. Example outcomes include licensing assets, project funding/PhD, and research collaborations.

Opportunities sought

-  Technologies
-  Academics and expertise
-  Centres of excellence
-  Research projects
-  Spinout companies

Submissions

Please submit relevant, non-confidential opportunities online [here](#)

Deadline: **29th January 2024 - 11:59 pm GMT**

Have any questions?

Contact our team at discover@in-part.co.uk